

2SB0936 (2SB936), 2SB0936A (2SB936A)

Silicon PNP epitaxial planar type

For low-voltage switching

■ Features

- Low collector-emitter saturation voltage $V_{CE(sat)}$
- High-speed switching
- N type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment.

■ Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

Parameter		Symbol	Rating	Unit
Collector-base voltage (Emitter open)	2SB0936	V_{CBO}	-40	V
	2SB0936A		-50	
Collector-emitter voltage (Base open)	2SB0936	V_{CEO}	-20	V
	2SB0936A		-40	
Emitter-base voltage (Collector open)		V_{EBO}	-5	V
Collector current		I_C	-10	A
Peak collector current		I_{CP}	-20	A
Collector power dissipation		P_C	40	W
	$T_a = 25^{\circ}\text{C}$		1.3	
Junction temperature		T_j	150	$^{\circ}\text{C}$
Storage temperature		T_{stg}	-55 to +150	$^{\circ}\text{C}$

■ Electrical Characteristics $T_C = 25^\circ\text{C} \pm 3^\circ\text{C}$

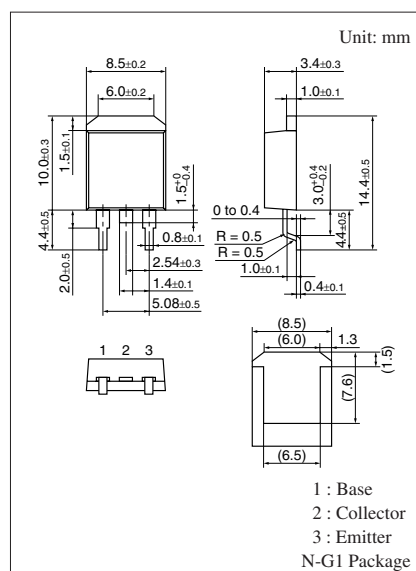
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	2SB0936 2SB0936A	V_{CEO}	$I_C = -10\text{ mA}, I_B = 0$	-20		V
				-40		
Collector-base cutoff current (Emitter open)	2SB0936 2SB0936A	I_{CBO}	$V_{CB} = -40\text{ V}, I_E = 0$		-50	μA
					-50	
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = -5\text{ V}, I_C = 0$			-50	μA
Forward current transfer ratio	h_{FE1}^* h_{FE2}	$V_{CE} = -2\text{ V}, I_C = -0.1\text{ A}$	45			—
		$V_{CE} = -2\text{ V}, I_C = -3\text{ A}$	90		260	
Base-emitter voltage	$V_{BE(sat)}$	$I_C = -10\text{ A}, I_B = -0.33\text{ A}$			-1.5	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -10\text{ A}, I_B = -0.33\text{ A}$			-0.6	V
Transition frequency	f_T	$V_{CE} = -10\text{ V}, I_C = -0.5\text{ A}, f = 10\text{ MHz}$		100		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = -10\text{ V}, I_E = 0, f = 1\text{ MHz}$		400		pF
Turn-on time	t_{on}	$I_C = -3\text{ A},$ $I_{B1} = -0.1\text{ A}, I_{B2} = 0.1\text{ A}$ $V_{CC} = -20\text{ V}$		0.1		μs
Storage time	t_{stg}			0.5		μs
Fall time	t_f			0.1		μs

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

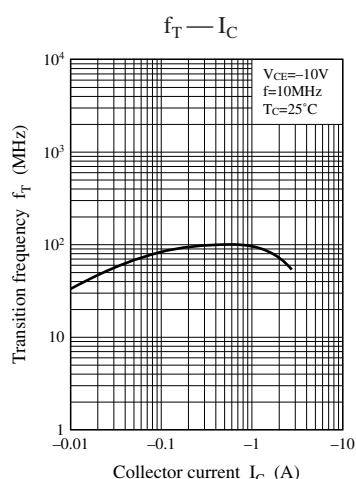
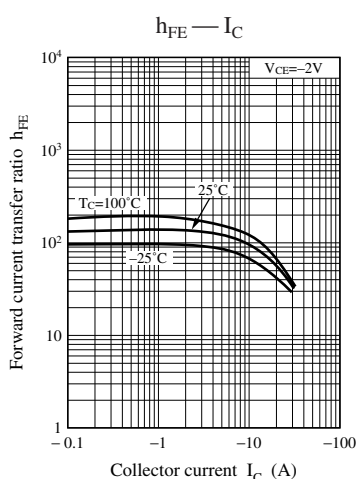
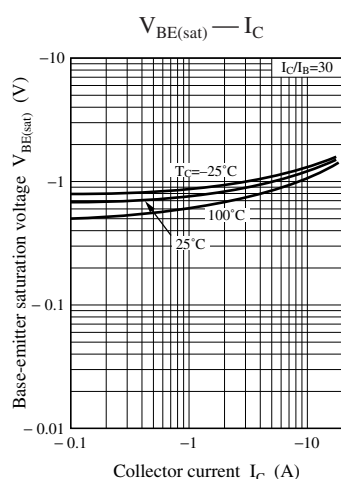
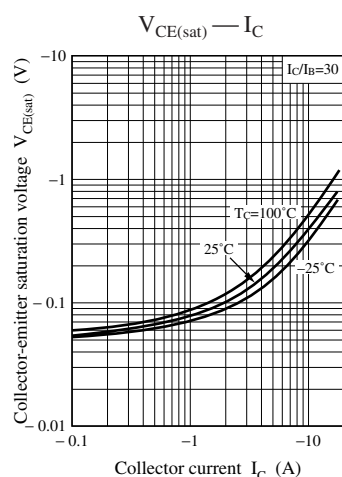
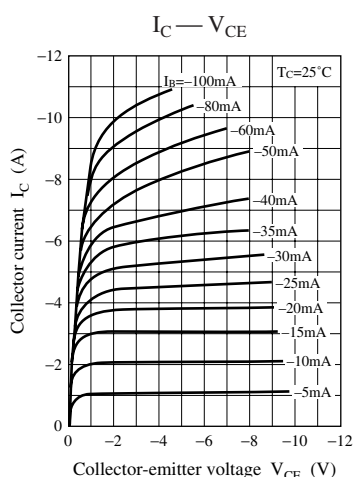
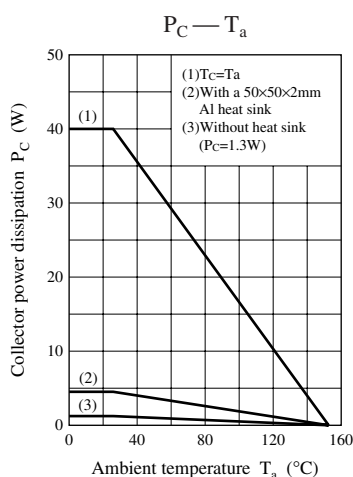
2. *: Rank classification

Rank	Q	P
h_{FE1}	90 to 180	130 to 260

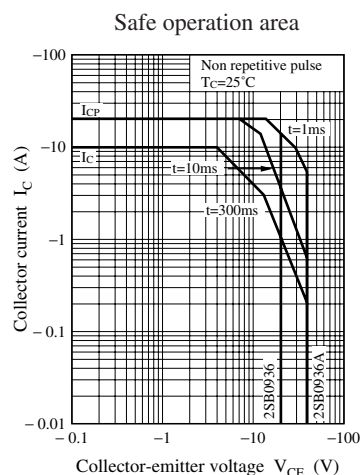
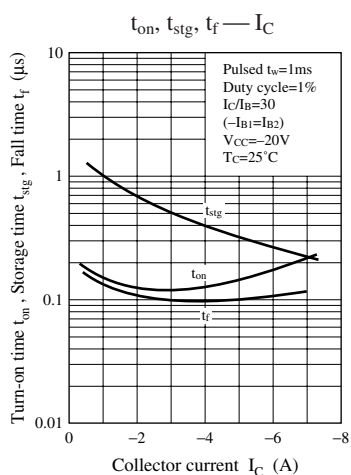
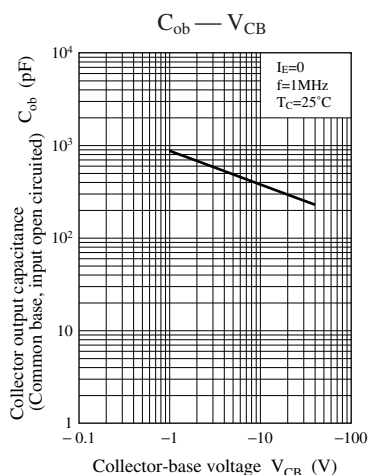
Note) The part number in the parenthesis shows conventional part number.

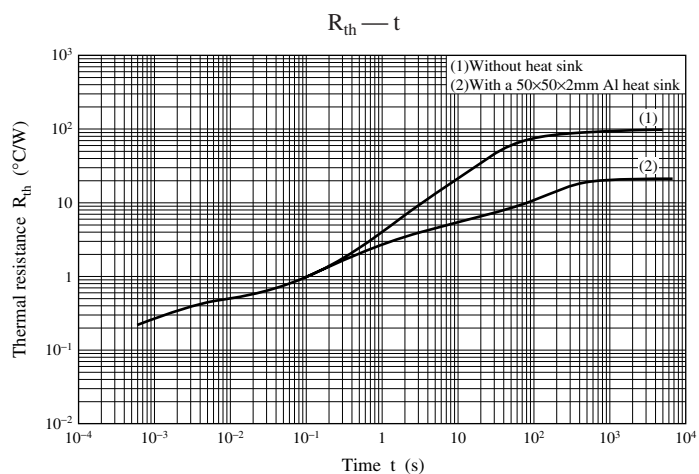


Note) Self-supported type package is also prepared.



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